

DESCRIPTION

The SPN8882 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. The SPN8882 has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON) and fast switching speed.

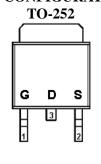
APPLICATIONS

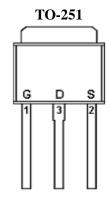
- Power Management in Note book
- Powered System
- DC/DC Converter
- Load Switch

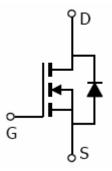
FEATURES

- 30V/40A, RDS(ON)= $10m\Omega$ @VGS=10V
- 30V/40A, RDS(ON)= $14m\Omega@VGS=4.5V$
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ TO-252,TO-251 package design

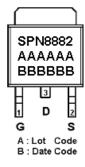
PIN CONFIGURATION







PART MARKING





2011/04/19 Ver.4

PIN DESCRIPTION						
Pin	Symbol	Description				
1	G	Gate				
2	S	Source				
3	D	Drain				

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN8882T252RG	TO-252	SPN8882
SPN8882T251TG	TO-251	SPN8882

SPN8882T252RG: Tape Reel; Pb – FreeSPN8882T251TG: Tube; Pb – Free

ABSOULTE MAXIMUM RATINGS

(Ta=25°C Unless otherwise noted)

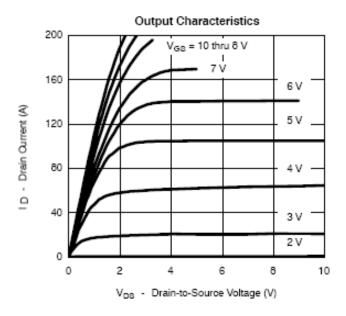
Parameter			Symbol	Typical	Unit
Drain-Source Voltage			Vdss	30	V
Gate –Source Voltage			VGSS	±20	V
Continuous Drain Current	ntinuous Drain Current $ \frac{T_A=25^{\circ}C}{T_A=100^{\circ}C} $		ID	60 40	A
Pulsed Drain Current			IDM	100	A
Continuous Drain Current			Is	50	A
Single Pulse Drain to Source Avalanche Energy – Starting (TJ=25°C, VDD=27V, VGS=10V, IAS=28A, L=0.1mH)			Eas	41	mJ
	TA=25°C	TO-252-2L	PD	40	
Power Dissipation		TO-251		55	W
Operating Junction Temperature			Тл	150	$^{\circ}\!\mathbb{C}$
Storage Temperature Range			Tstg	-55/150	$^{\circ}\!\mathbb{C}$
Thermal Resistance-Junction to Ambient			RөJA	100	°C/W

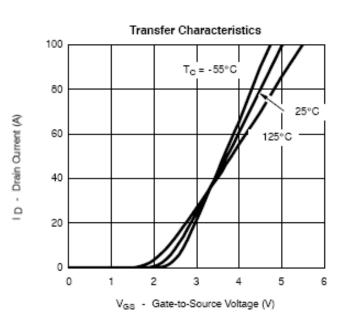
ELECTRICAL CHARACTERISTICS

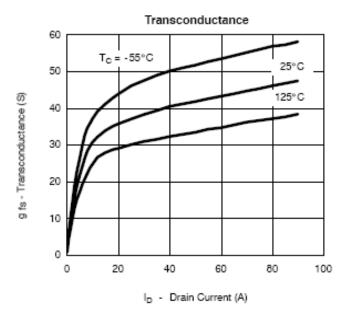
(TA=25°C Unless otherwise noted)

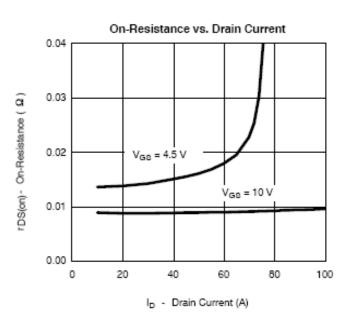
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage V(BR)DSS VGS		$V_{GS} = 0V$, $I_D = 250uA$	30			V	
Gate Threshold Voltage	VGS(th)	$V_{DS} = V_{GS,IDS} = 250uA$ 0.8			2.4		
Gate Leakage Current	Igss	$V_{DS} = 0V, V_{GS} = \pm 20 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 24V, V_{GS} = 0V$ $V_{DS} = 24V, V_{GS} = 0V,$ $T_{J} = 125C$	= 24V,V _{GS} =0V = 24V,V _{GS} =0V,		1 100	uA	
Drain-Source On-Resistance	RDS(on)	V _{GS} = 10V, ID = 35A V _{GS} = 4.5V, ID = 35A		0.008 0.012	0.010 0.014	Ω	
Forward Transconductance	gfs	$V_{DS} = 15V$, $I_{D} = 20 A$	10			S	
Diode Forward Voltage	Vsd	$I_F = 40 \text{ A}, V_{GS} = 0V$		1.0	1.5	V	
Dynamic							
Total Gate Charge	Qg			12	20	nC	
Gate-Source Charge	Qgs	$V_{DS} = 15V, V_{GS} = 5V,$ $I_{D} = 50 A$		4			
Gate-Drain Charge	Qgd	30 N		5			
Input Capacitance	Ciss			1500		pF	
Output Capacitance	Coss	$V_{GS} = 0V$, $V_{DS} = 25V$, F=1MHz		320			
Reverse Transfer Capacitance	Crss	T TIVITIZ		200			
т. О. Т.	td(on)			8	12	ns	
Turn-On Time	tr	$(V_{DD} = 15 \text{ V}, I_D = 50 \text{ A},$		10	15		
T. OMT.	td(off)	$V_{GS}=10V,R_G=2.5\Omega)$		18	30		
Turn-Off Time	tf]		6	9		

TYPICAL CHARACTERISTICS

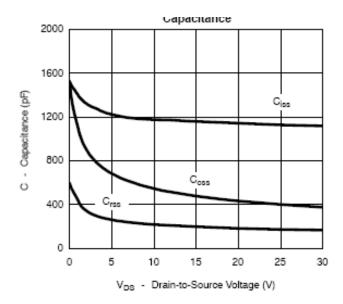


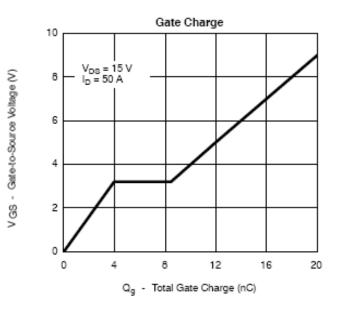


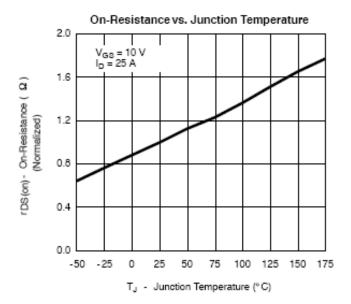


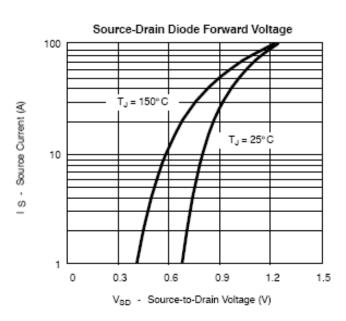


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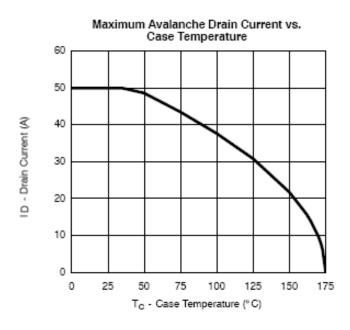


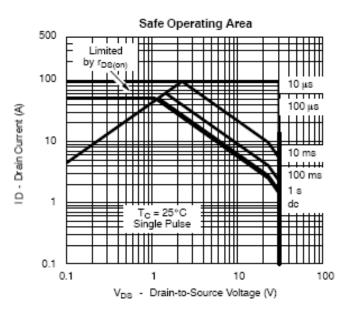


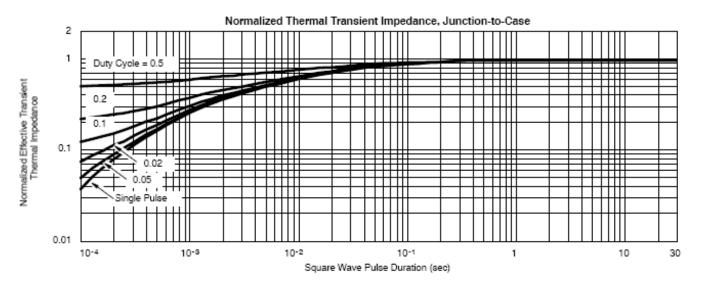




TYPICAL CHARACTERISTICS

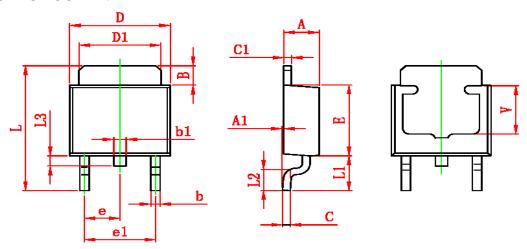








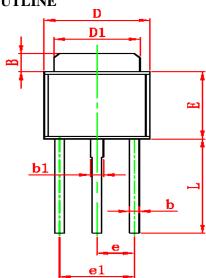
TO-252 PACKAGE OUTLINE

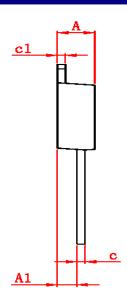


Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
Е	5.400	5.700	0.213	0.224	
е	2.300) TYP	0.091 TYP		
e1	4.500	4.700	0.177	0.185	
L	9.500	9.900	0.374	0.390	
L1	2.550	2.900	0.100	0.114	
L2	1.400	1.780	0.055	0.070	
L3	0.350	0.650	0.014	0.026	
V	3.80	REF	0.150 REF		



TO-251 PACKAGE OUTLINE





Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	2.200	2.400	0.087	0.094	
A1	1.020	1.270	0.040	0.050	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300 TYP		0.091 TYP		
e1	4.500	4.700	0.177	0.185	
L	7.500	7.900	0.295	0.311	

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